

## PATENT ASSIGNMENT COVER SHEET

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|   |                                      |
|---|--------------------------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT                       |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT                           |
| <b>CONVEYING PARTY DATA</b>   |                                      |
| <b>Name</b>   | <b>Execution Date</b>                |
| MARCOS A. SIMPLICIO JR  | 03/08/2019                           |
| MARCOS V. M. SILVA  | 03/08/2019                           |
| RENAN C. A. ALVES   | 03/08/2019                           |
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| <b>State/Country:</b>   | KOREA, REPUBLIC OF                   |
| <b>Postal Code:</b>   | 07336                                |
| <b>Name:</b>  | UNIVERSIDADE DE SAO PAULO            |
| <b>Street Address:</b>  | 374 CIDADE UNIVERSITARIA             |
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| <b>State/Country:</b>   | BRAZIL                               |
| <b>Postal Code:</b>   | 05508-220                            |
| <b>PROPERTY NUMBERS Total: 1</b>  |                                      |
| <b>Property Type</b>  | <b>Number</b>                        |
| <b>Application Number:</b>  | 16330075                             |
| <b>CORRESPONDENCE DATA</b>  |                                      |
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|   |                |
|---|----------------|
| <b>SIGNATURE:</b>   | /Harry S. Lee/ |
| <b>DATE SIGNED:</b>   | 02/10/2021     |
| <b>Total Attachments: 2</b><br>source=2060-5818_Assignment#page1.tif<br>source=2060-5818_Assignment#page2.tif |                |

## ASSIGNMENT

|  |   |                          |
|--|---|--------------------------|
| (1-8) <i>Insert Name(s) of Inventor(s)</i>   | (1) Marcos A. SIMPLICIO JR.<br>(2) Marcos V. M. SILVA<br>(3) Renan C. A. ALVES<br>(4)   | (5)<br>(6)<br>(7)<br>(8) |
|  | In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to   |                          |
| (9) <i>Insert name of Assignee</i>   | (9) LG Electronics Inc. and UNIVERSIDADE DE SAO PAULO   |                          |
| (10) <i>Insert state of Incorporation of Assignee</i>  | (10) Republic of Korea and Brazil   |                          |
| (11) <i>Insert address of Assignee</i>   | (11) 128, Yeoui-daero, Yeongdeungpo-gu, Seoul, 07336, Republic of Korea and<br>Universidade de Sao Paulo Rua da Reitoria, 374 Cidade Universitaria<br>Armando de Salles Oliveira 05508-220 Sao Paulo, Brazil<br>(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as |                          |
| (12) <i>Insert identification of Invention, such as Title, Case Number or Foreign Application Number</i> | (12) <b>LIGHTWEIGHT AND ESCROW-LESS AUTHENTICATED KEY AGREEMENT FOR THE INTERNET OF THINGS</b><br><br>for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.                            |                          |

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints **the Attorneys associated with Customer No. 35884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 08/Mar/2019 Signature of Inventor (1) Moritz

Date: 08/Mar/2019 Signature of Inventor (2) Mason Vinicius Masel da Silva

Date: 08/Mar/2019 Signature of Inventor (3) Ram Chikar